a spin on deposition process. The underflow adhesive is selected from a group of materials including, but not limited to, epoxies, poly-imides, or silicone-polyimides copolymers and includes one or more of the following components: epoxy resin, a hardener, a catalyst initiator, a coloring dye and an inorganic filler.

Please **replace** original paragrpah **[0011]** with the following **amended** paragraph **[0011]**:

In the initial step as illustrated in Figure 2(a), a number of underbump metallization pads 110 are formed on the surface of the die 102. The underbump metallization pads 110 may be formed by a number of conventional processes. For example, a layer of solder or other conductive metal is applied on the surface of the die 102. The surface is then masked and etched, leaving the pads 110. In the next step as illustrated in Figure 2(b), solder paste islands 112 are formed on the pads 110. After the solder paste islands 112 are in place, corresponding solder balls 106 are formed by heating the wafer 100 causing the solder to reflow forming the solder balls 106. The resulting structure is illustrated in Figure 2(c). The underbump metallization pad 110 also provides a barrier metal between the solder ball 106 and the interconnects within flip chip die 102.